

## **CLAIM AMENDMENTS**

Please cancel claims 1-5 and 8-12.

Please amend claim 6, and add new claims 13-21 as follows:

Claims 1-5 (cancelled).

Claim 6 (currently amended): A circuit board for a semiconductor device,  
comprising: as claimed in claim 1,

a plurality of pads on which the semiconductor device is to be mounted,  
said pads being formed on the circuit board, and said pads being disposed in a  
first line;

a plurality of terminals formed on a side edge of the circuit board, said  
terminals being disposed in a second line, which is in parallel to said first line of  
said pads;

a resist film covering an area on the circuit board between said pads and  
said terminals; and

a barrier formed between said first line of said pads and said second line  
of said terminals, wherein said barrier including includes a plurality of trench  
disposed along said terminals, and said trenches being formed in said resist film.

Claim 7 (original): A circuit board for a semiconductor device as claimed in  
claim 6, wherein said trenches are parallel to each other.

Claims 8-12 (cancelled).

Claim 13 (new): A circuit board for a semiconductor device as claimed in claim 6, wherein a distance between trances is 1 mm.

Claim 14 (new): A circuit board for a semiconductor device as claimed in claim 13, wherein said terminals are disposed in a certain length which is shorter than a length of said barrier.

Claim 15 (new): A circuit board for a semiconductor device as claimed in claim 13, wherein a depth of the barrier equals the thickness of the resist film.

Claim 16 (new): A circuit board for a semiconductor device as claimed in claim 6, wherein each trench had a width of 1 mm.

Claim 17 (new): A circuit board for a semiconductor device as claimed in claim 16, wherein said terminals are disposed in a certain length which is shorter than a length of said barrier.

Claim 18 (new): A circuit board for a semiconductor device as claimed in claim 16, wherein a depth of the barrier equals the thickness of the resist film.

Claim 19 (new): A circuit board for a semiconductor device as claimed in claim 13, wherein each trench had a width of 1 mm.

Claim 20 (new): A circuit board for a semiconductor device as claimed in claim 19, wherein said terminals are disposed in a certain length which is shorter than a length of said barrier.

Claim 21 (new): A circuit board for a semiconductor device as claimed in claim 19, wherein a depth of the barrier equals the thickness of the resist film.